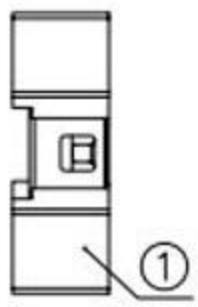
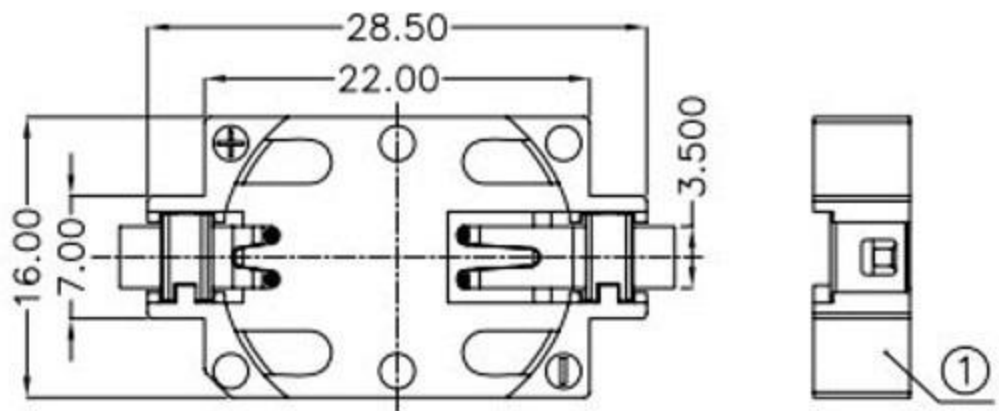




REV.	ECN NO.	REVISED	DATE

- 1.MATERIAL:  
 a.HOUSING:LCP UL94V-0  
 b.CONTACT:PHOSPHOR BRONZE (SURFACE PLATING:Au1u")  
 SEE ORDERING INFORMATION
- 2.ELECTRIC:  
 a.CONTACT RESISTANCE: 30 MILLIOHMS MAX  
 b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN  
 c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL  
 d.OPERATING TEMPERATURE: -25°C~ +85°C



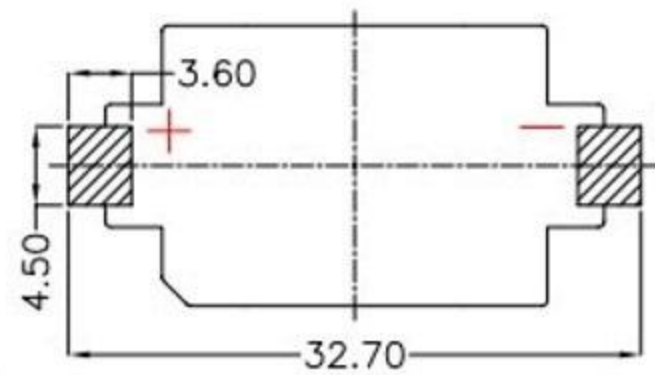
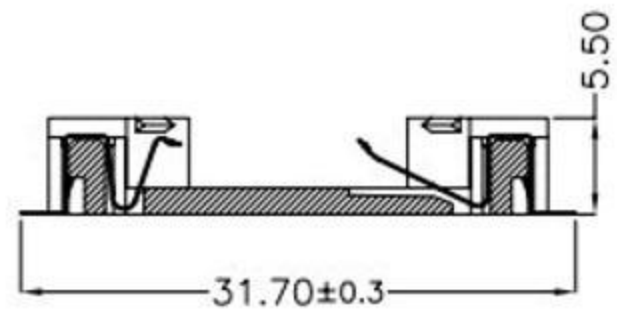
ORDERING INFORMATION

电池座系列

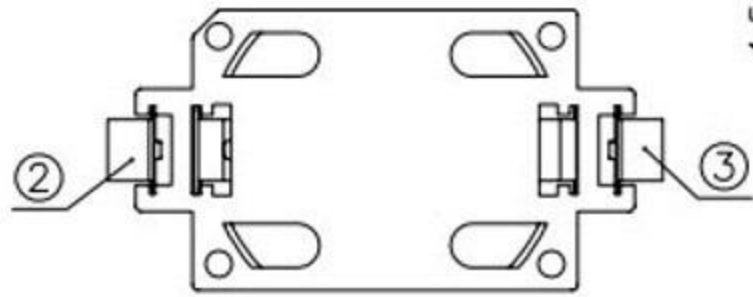
PLATING:  
 A-Au1u"  
 J-Ni100u"~120u"  
 K-Sn100u"~120u"

MATERIAL:  
 1A-PBT BLACK  
 1B-PA66 BLACK  
 2A-PPA BROWN  
 2B-PPA BLACK  
 3A-PPS BROWN  
 3B-PPS BLACK  
 4A-LCP WHITE  
 4B-LCP BLACK  
 5A-PA6T WHITE  
 5B-PA6T BLACK

SMT 180° TYPE



PCB Layout Diagram  
Top View



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X ±0.30 X.X ±0.25 X.XX ±0.20 X.XXX ±0.10

ANGLES: X ±1° X.X ±0.5°

**廣東科斯達電子科技有限公司**

DSND	DATE	2017-07-11	TITLE:
CHKD	DATE	2017-07-11	
APVD	DATE	2017-07-11	PART NO.:
WEIGHT: 1.49g	SCALE: 2:1	SIZE: A4	VIEW:
SHEET 1 OF 1	UNIT: mm	REV.: A/0	OBJECT: MY
			DRAW NO.

NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR
3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.15mm	Gold Plating and Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.15mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	LCP	WHITE